

We claim:

1. An improved wafer handler, comprising:

A ring with an upper surface and orifices for applying a
5 vacuum to the surface of a semiconductor wafer;

a hub;

spokes connecting said ring to said hub; and

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orifices in said spokes through which water and nitrogen
can be passed unto the surface of said semiconductor wafer.

2. The method of claim 1 wherein said improved wafer handler is
15 connected to a chemical mechanical polishing tool.

3. The method of claim 1 wherein said ring is 0.01 to 0.3 inches
thick.

20 4. The method of claim 1 wherein said hub further comprises a
diverter valve.

5. A CMP processing tool with improved wafer handling,
comprising:

a wafer handler for holding a semiconductor wafer while
5 processing; and

a pedestal for loading and unloading said semiconductor
wafer to said wafer handler wherein said pedestal further
comprises;

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a ring with an upper surface and orifices for applying a
vacuum to the surface of a semiconductor wafer;

a hub;

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spokes connecting said ring to a hub; and

orifices in said spokes through which water and nitrogen
can be passed unto the surface of said semiconductor wafer.

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6. The method of claim 5 wherein said ring is 0.01 to 0.3 inches
thick.

7. The method of claim 5 wherein said hub further comprises a diverter valve.

8. An improved wafer handler, comprising:

A ring with an upper surface and orifices for applying a vacuum to the surface of a semiconductor wafer;

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a hub comprising a diverter valve.

spokes connecting said ring to said hub; and

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orifices in said spokes through which water and nitrogen can be passed unto the surface of said semiconductor wafer.

9. The method of claim 8 wherein said improved wafer handler is connected to a chemical mechanical polishing tool.

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10. The method of claim 8 wherein said ring is 0.01 to 0.3 inches thick.

11. The method of claim 8 wherein said diverter valve further
20 comprises:

a housing with an internal top surface and an internal bottom surface; and

a valve ring contained in said housing wherein said valve ring moves to the internal bottom surface on the application of a vacuum and said valve ring moves to the internal top surface on the application of water or nitrogen.

12. A diverter valve, comprising:

a housing with an internal top surface and an internal bottom surface; and

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a valve ring contained in said housing wherein said valve ring moves to the internal bottom surface on the application of a vacuum to said housing.

10 13. The diverter valve of claim 12 further comprising:

a plurality of tubes connected to said internal bottom surface wherein said valve ring covers said plurality of tubes when a vacuum is applied to said housing.

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